3.0mmx1.0 mm RIGHT ANGLE SMD CHIP LED LAMP

Part Number: KPA-3010MGC Mega Green

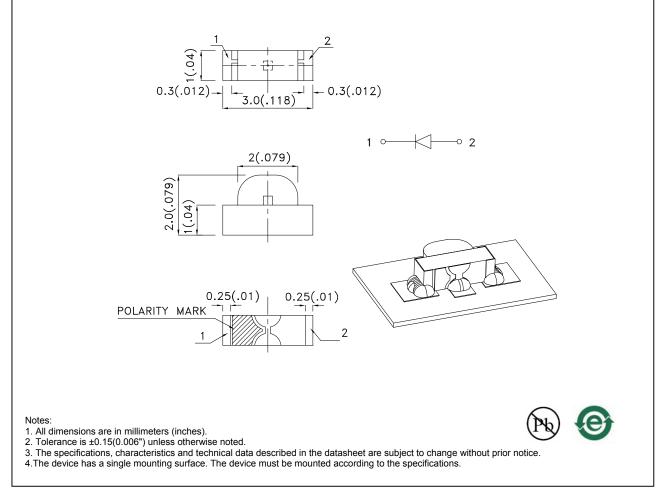
Features

- 3.0mmx1.0mm right angle SMT LED, 2.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for back light and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- RoHS compliant.

Description

The Mega Green source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.

Package Dimensions



SPEC NO: DSAA9051 APPROVED: WYNEC REV NO: V.17B CHECKED: Allen Liu DATE: JAN/03/2013 DRAWN: C.H.Han PAGE: 1 OF 5 ERP: 1203000583

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KPA-3010MGC	Mega Green (AlGaInP)	Water Clear	40	60	120°

Notes:

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Mega Green	570		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	IF=20mA
С	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Mega Green	2.1	2.5	V	I⊧=20mA
lr	Reverse Current	Mega Green		10	uA	VR=5V

Notes:

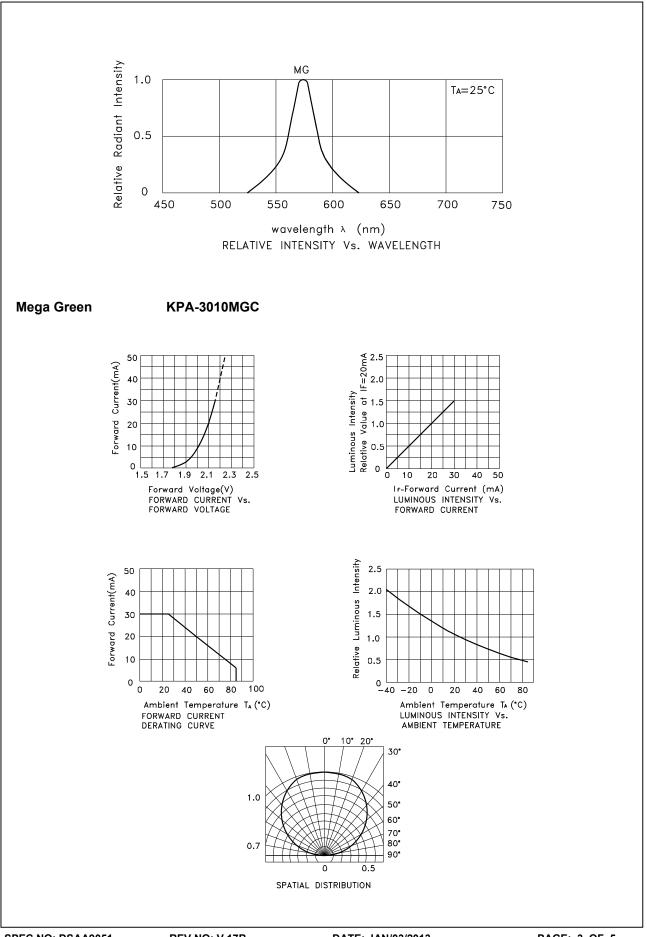
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Mega Green	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

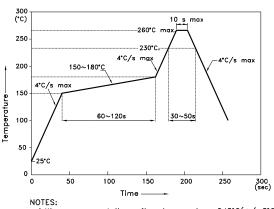
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KPA-3010MGC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

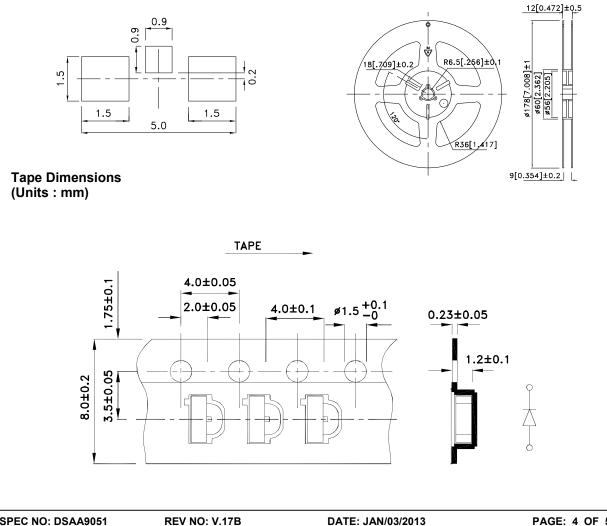
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)





SPEC NO: DSAA9051 APPROVED: WYNEC

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